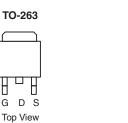


Vishay Siliconix

Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	60			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.0035			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0.0050			
I _D (A)	120			
Configuration	Single			



GOLIE

D

N-Channel MOSFET

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- AEC-Q101 Qualified^d
- 100 % $R_{\rm q}$ and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ORDERING INFORMATION	
Package	TO-263
Lead (Pb)-free and Halogen-free	SQM120N06-04L-GE3

ABSOLUTE MAXIMUM RATINGS	$(T_C = 25 \ ^\circ C, unless$	s otherwise noted	4)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	60	- v	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current ^a	T _C = 25 °C		120		
	T _C = 125 °C	I _D	120		
Continuous Source Current (Diode Conduction) ^a		I _S	120	А	
Pulsed Drain Current ^b		I _{DM}	480		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	75		
Single Pulse Avalanche Energy		E _{AS}	281	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	D	375	W	
	T _C = 125 °C	P _D	125		
Operating Junction and Storage Temperature	Range	T _J , T _{stg}	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	40	°C/W
unction-to-Case (Drain)		R _{thJC}	0.4	0/10

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).

d. Parametric verification ongoing.

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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static					•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0, I_D = 250 \ \mu A$		60	-	-	v	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		1.5	2.0	2.5		
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	± 100	nA	
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1.0		
	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA	
		$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$	-	-	350		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α	
Drain-Source On-State Resistance ^a		V _{GS} = 10 V	I _D = 30 A	-	0.0028	0.0035	Ω	
	P	V _{GS} = 10 V	I _D = 30 A, T _J = 125 °C	-	-	0.0060		
	R _{DS(on)}	$V_{GS} = 10 V$	I _D = 30 A, T _J = 175 °C	-	-	0.0080		
		$V_{GS} = 4.5 V$	I _D = 20 A	-	0.004	0.0050		
Forward Transconductanceb	9 _{fs}	V _{DS}	= 15 V, I _D = 30 A	-	109	-	S	
Dynamic ^b	·				-			
Input Capacitance	C _{iss}		V _{DS} = 25 V, f = 1 MHz	-	7300	9125	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$		-	935	1170		
Reverse Transfer Capacitance	C _{rss}			-	647	810		
Total Gate Charge ^c	Qg		V _{DS} = 30 V, I _D = 110 A	-	184	276	nC	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V		-	24.7	-		
Gate-Drain Charge ^c	Q _{gd}			-	50.4	-		
Gate Resistance	Rg	f = 1 MHz		0.5	1.1	1.6	Ω	
Turn-On Delay Time ^c	t _{d(on)}			-	19	29		
Rise Time ^c	t _r	$\label{eq:VDD} \begin{array}{l} V_{DD}=30~\text{V},~\text{R}_{\text{L}}=0.27~\Omega\\ \text{I}_{\text{D}}\cong110~\text{A},~\text{V}_{\text{GEN}}=10~\text{V},~\text{R}_{\text{g}}=2.5~\Omega \end{array}$		-	23	35	- ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	83	125		
Fall Time ^c	t _f			-	35	53		
Source-Drain Diode Ratings and Chara	acteristics ^b					•		
Pulsed Current ^a	I _{SM}			-	-	480	Α	
Forward Voltage	V _{SD}	I _F = 100 A, V _{GS} = 0		-	0.9	1.5	V	

Notes

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

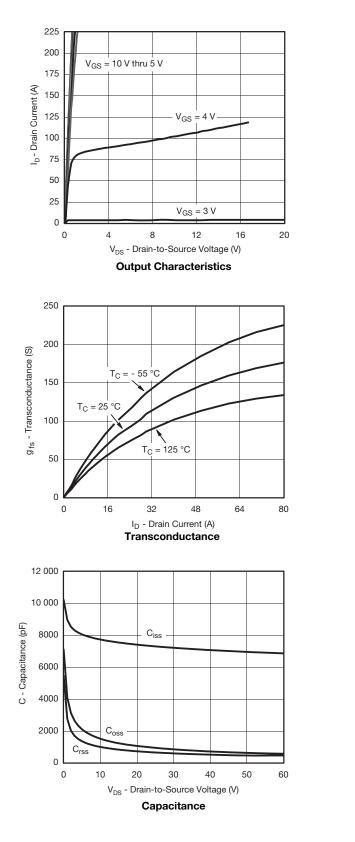
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

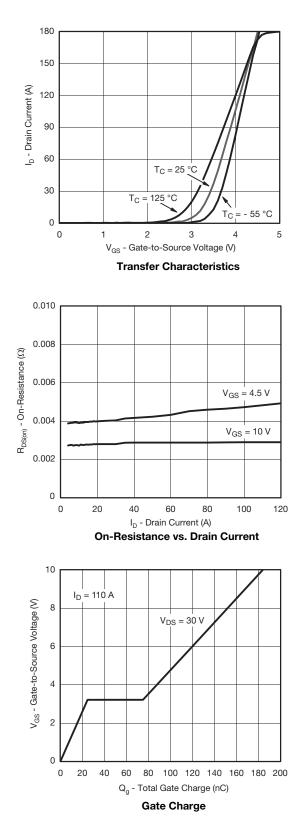




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TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)





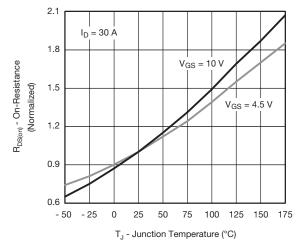
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Document Number: 67046

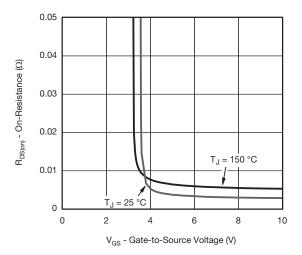


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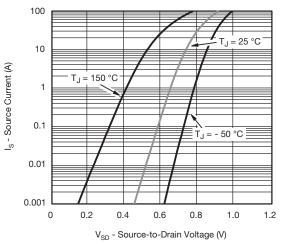
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



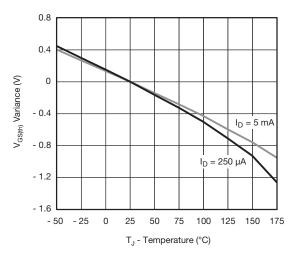
On-Resistance vs. Junction Temperature



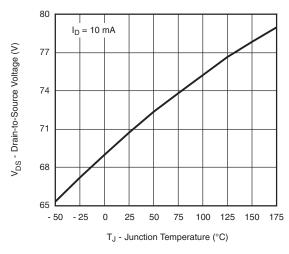
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage



Threshold Voltage



Drain Source Breakdown vs. Junction Temperature

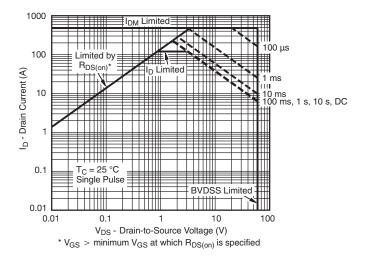
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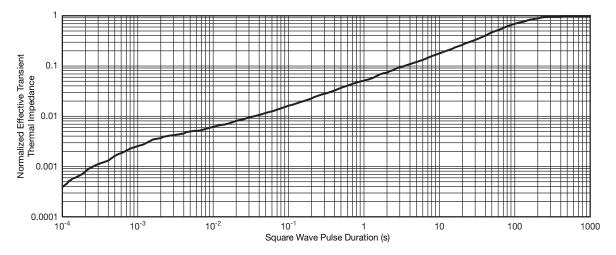


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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Safe Operating Area



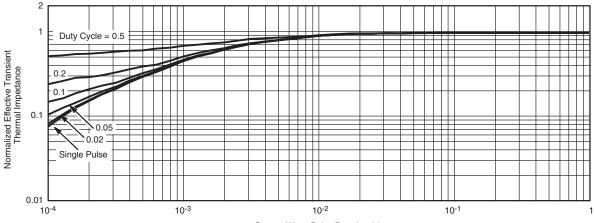
Normalized Thermal Transient Impedance, Junction-to-Ambient

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THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

Note

• The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg?67046</u>.

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